

**REMARKS**

Claims 1-3, 7 and 12 are pending in this application. By this Amendment, claim 1 is amended, claim 12 is added, and claims 4-6 are canceled without prejudice to or disclaimer of the subject matter recited therein. Support for the amendment to claim 1 can be found, for example, in Fig. 7 and page 13, lines 6-16 of the specification. Support for new claim 12 can be found, for example, in Fig. 8. No new matter is added.

**I. Rejection of the Claims**

The Office Action rejects claims 1-7 under 35 U.S.C. §103(a) over Tsuneo, JP-A-09-051020 in view of Furusawa, U.S. Patent Application Publication No. 2002/0151171. The rejection of canceled claims 4-6 is moot. The rejection of claims 1-3 and 7 is respectfully traversed.

The combination of Tsuneo and Furusawa fails to disclose or suggest forming an insulating section adjacent to the chip component by applying a force between the substrate and the chip component so that a portion of the adhesive is pressed out to a region adjacent to the chip component, so that the portion has a top higher from the substrate than the first surface, and so that the insulating section is formed of the portion of the adhesive, as recited in claim 1.

Tsuneo discloses that an insulating section 11 is formed after the semiconductor chip 3 has been mounted and the adhesive has been pushed out (overflowing layer 19) (see Figs. 3-5). Thus, Tsuneo requires more materials and more steps to form the semiconductor device than the method of claim 1. Further, Furusawa fails to overcome the deficiencies of Tsuneo. Therefore, the combination of Tsuneo and Furusawa fails to disclose or suggest forming an insulating section adjacent to the chip component by applying a force between the substrate and the chip component so that a portion of the adhesive is pressed out to a region adjacent to the chip component, so that the portion has a top higher from the substrate than the first

surface, and so that the insulating section is formed of the portion of the adhesive, as recited in claim 1. Thus, claim 1 is patentable over the applied references.

Because claims 2, 3 and 7 incorporate the subject matter of claim 1, these claims also are patentable over the combination of Tsuneo and Furusawa. Therefore, it is respectfully requested that the rejection be withdrawn.

**II. New Claim 12**

Tsuneo fails to disclose or suggest a chip component having a side surface that is inclined so as to descend in an outward direction from a first surface of the chip component, and forming an insulating section adjacent to the chip component and on the side surface, as recited in new claim 12. The claimed inclined side surface makes it easier to apply thereon the insulating section with an inclined surface. Furusawa also fails to disclose or suggest these features. Thus, new claim 12 also is patentable over the applied references.

**III. Conclusion**

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of all pending claims are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,  
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Attachment:

Request for Continued Examination

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